**Product Type:** LTCC Materials  
**Product Name:** TC0101

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**Co-Firing Gold Fill**

**Description**

TC0101 is a pure Au via fill which provides excellent compatibility with HeraLock® HL2000 during the cofiring process.

After firing it results in a dense filled via with minimal posting. It can be used to manufacture high reliability all gold LTCC microcircuits.

**Key Benefits**

- Low resistivity
- Compatible with HeraLock® HL2000
- Minimal posting
- Pb and Cd free
- REACH¹ and ROHS² compliant

**Typical Properties**

**Viscosity:**  
700 – 1000 Kcps, Cone and Plate at 10 sec⁻¹, 25 °C

**Solids:**  
87.0 ± 1.0 %

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**Recommended Processing Guidelines**

**Printing:**
Print through a stencil or the backing materials of the tape (2 – 3 mil PET) with moderate vacuum pull through.

**Drying:**
80 °C for 10 minutes

**Firing:**
See HeraLock® HL2000 data sheet

**Compatibility:**
HeraLock® HL2000 recommended product list

**Pitch:**
≥ 2.5 mil (62.5 µm) via diameter

**Thinner:**
RV-372

**Warranty:**
Material guaranteed to meet specifications for 3 months from date of shipment.

**Storage:**
Store in a dry location at 5 – 25 °C.  
**DO NOT REFRIGERATE.**
Allow paste to come to room temperature prior to opening. Spatulate well before using, as settling may occur during storage.
Legend:

1) REACH compliant according to the latest * Annex XIV to Regulation (EC) of the European Parliament and of the council on the Registration, Evaluation, Authorisation and Restriction of Chemicals ("REACH") by European Chemicals Agency and its subsequent amendments; the material does not contain any substance listed in Annex XIV.

2) RoHS compliant according to the latest * Directives (European Union) of Restriction of Hazardous Substances ("RoHS") and its subsequent amendments (including the exceptions related to Pb)